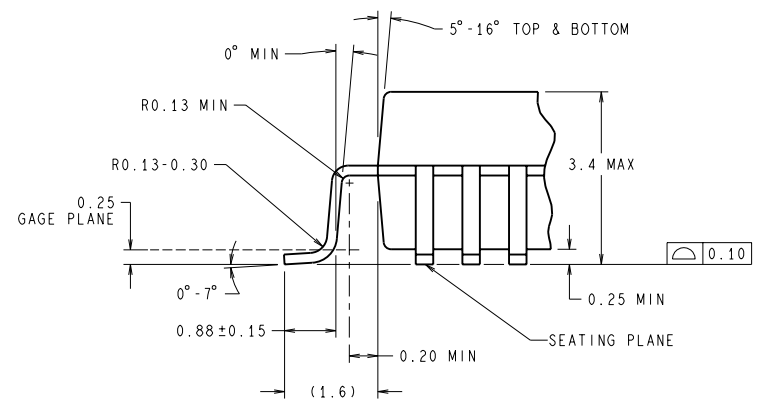
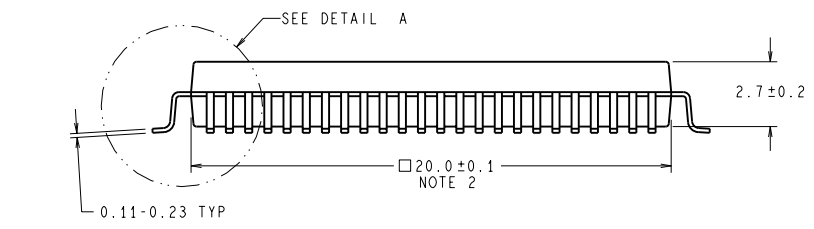
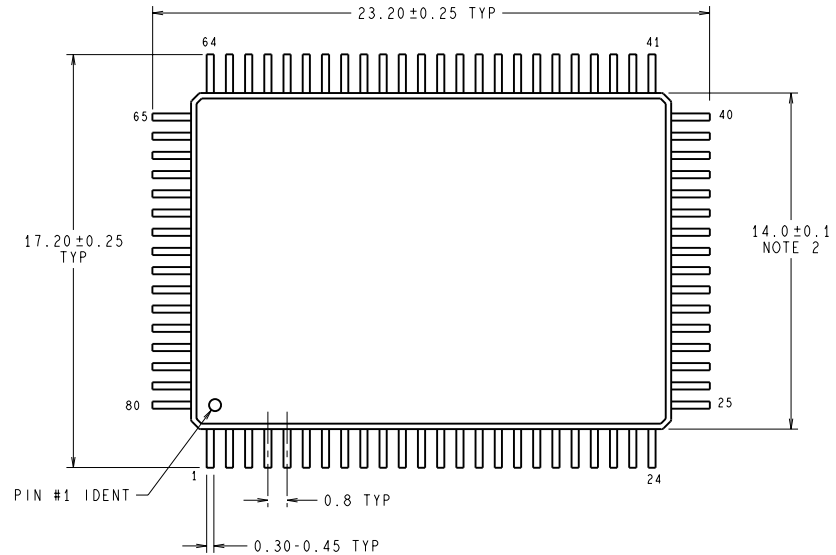


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
C	REVISE AND REDRAW PER JEDEC MS-022.	11033	07/12/95	DEG/



DETAIL A  
TYP, SCALE: 17X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:  
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)  
THICKNESS ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.  
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- REFERENCE JEDEC STANDARD MS-022, VARIATION GB-1,  
DATED FEB/95.

APPROVALS	DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	PQFP, JEDEC METRIC, 14 X 20 X 2.7mm, 80 LEAD		
DRAWN <i>D.E. Grady</i>	07/12/95		SCALE	SIZE	DRAWING NUMBER
DFTG. CHK.			N/A	C	MKT-VCC80A
ENGR. CHK.			DO NOT SCALE DRAWING		REV C
 PROJECTION INCH MM		SHEET 1 of 1			